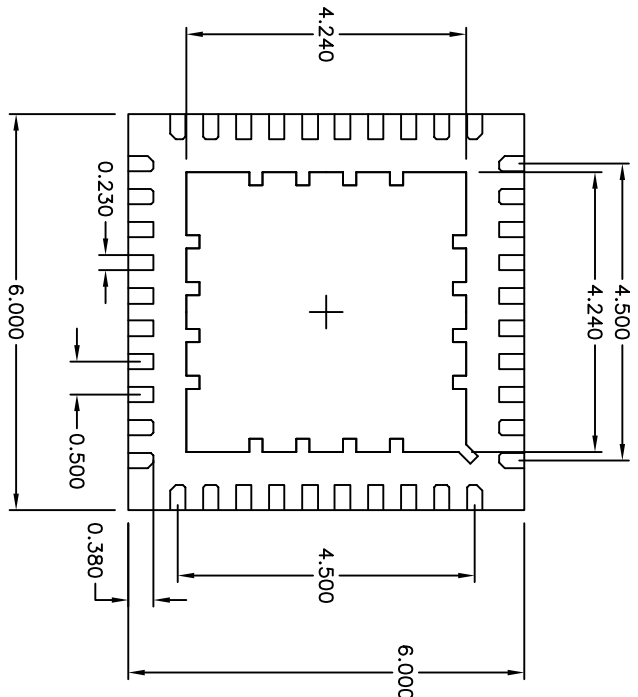
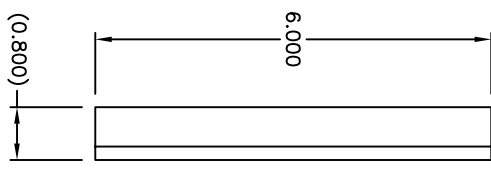
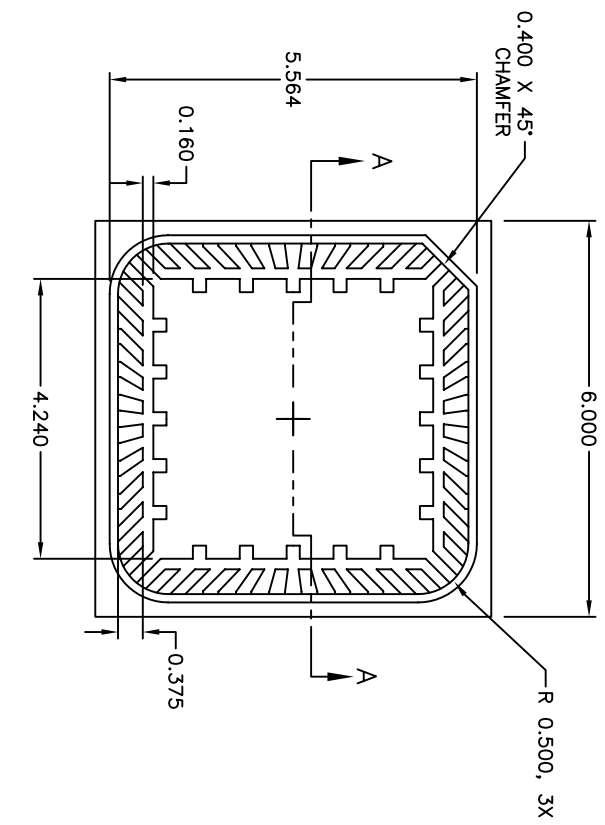
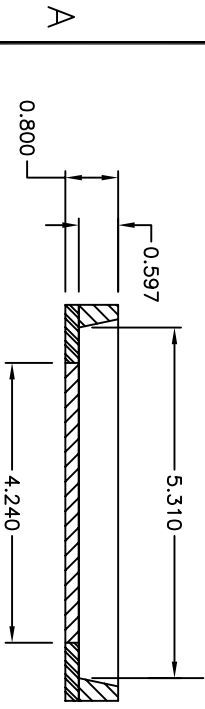


REVISIONS			
EON NO.	DATE	DESCRIPTION	APPROVED
10627	3/20/06	PRODUCTION RELEASE	D.BENAMANDO



TOP VIEW

BOTTOM VIEW



SECTION A-A

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEAD FRAME: COPPER, 194 FH.
 3. LEAD FINISH: FULL GOLD PLATE.
 4. FRAME THICKNESS: 0.2030 ±.0076.
 5. DIE PAD: 4.240mm X 4.240mm.
 6. DIE JEDEC OUTLINE: MO-220 (VJUD-5).

<p>THIRD ANGLE PROJECTION</p>	<p>UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS</p> <p>TOLERANCES ARE: X.XXX ± 0.015 X.XXXX ± .---</p> <p>ANGLES: ± 1°</p>
	<p>DO NOT SCALE DRAWING</p>
<p>DRAWN BY: GRIFFITTS</p> <p>APP BY: P. FLASKERUD</p> <p>CUSTOMER: ---</p>	<p>DATE: 3/19/06</p> <p>DATE: 3/20/06</p>

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40 Lead 6mm x 6mm
 MLP Open-Pak

SIZE: A	PART NO. MLP6X6-40-OP-01	REV: 1
SCALE: NONE	CAD FILE: MLP6X6-40-OP-01-R1.DWG	SHEET: 1 OF 1